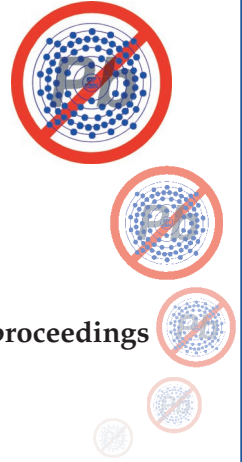




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Lead-Free Update Service

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- Provides updates on lead-free materials, applications, and reliability data
- Highlights new products with lead-free solders and lead-free flip chip bumping
- Includes Japanese newspaper and journal articles and major international conference proceedings
- Provides abstracts for most listings
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September 13, 2002 (TOKYO) – JVC announced that it has been using Sn-Zn-system, lead-free solders in printers for business use since April 2002. The company said it decided to adopt lead-free solder (composition: Sn-8 Zn-3Bi), because of its low melting point.

Reaction Mechanism and Reliability of the Interface between Sn-Ag-X Solders (X-Cu, Bi, Au) and Ni-Plating Precoated With Au, 8th Symposium on "Microjoining and Assembly Technology in Electronics", 231-236, January 31- February 1, 2002;

Sample Listings

Packaging Technology for High Performance UNIX Server, IMAPS International Symposium on Microelectronics Conference, September 4-6, 2002, pp. 27-32. Fujitsu has developed new high performance organic build-up substrate modules, MCMs and SCMs, for high performance servers. The MCM is 150 mm x 120mm x 61 mm on which two bare chip processors, one controller and ten SRAM packages are mounted. Lead-free solder bumps are used for the flip chip interconnect.

Special Report: Electronics Packaging and Mounting (Jisso) Technology Prospects: The Latest Wafer Level Packaging Technology Trends, pages 144-149. Wafer level CSP can expect to be widely used in cell phone applications. Although there are a variety of types of wafer level CSP, the one emerging as the strongest candidate for mass production in this area is the photolithography redistribution type. The encapsulation type wafer level CSP process is introduced. Efforts to achieve lead-free compatibility and stacked structures are described. 9 figures, 2 tables.

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